Complementary Power Transistors

DPAK For Surface Mount Applications

Designed for general purpose amplifier and low speed switching applications.

Features

- Lead Formed for Surface Mount Applications in Plastic Sleeves
- Straight Lead Version in Plastic Sleeves ("1" Suffix)
- Lead Formed Version in 16 mm Tape and Reel ("T4" Suffix)
- Electrically Similar to Popular TIP31 and TIP32 Series
- Epoxy Meets UL 94, V-0 @ 0.125 in
- NJV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC–Q101 Qualified and PPAP Capable
- These Devices are Pb-Free and are RoHS Compliant

MAXIMUM RATINGS

Rating	Symbol	Max	Unit
Collector–Emitter Voltage MJD31, MJD32 MJD31C, MJD32C	V _{CEO}	40 100	Vdc
Collector–Base Voltage MJD31, MJD32 MJD31C, MJD32C	V _{CB}	40 100	Vdc
Emitter-Base Voltage	V _{EB}	5.0	Vdc
Collector Current – Continuous	Ι _C	3.0	Adc
Collector Current – Peak	I _{CM}	5.0	Adc
Base Current	Ι _Β	1.0	Adc
Total Power Dissipation @ T _C = 25°C Derate above 25°C	PD	15 0.12	W W/°C
Total Power Dissipation @ T _A = 25°C Derate above 25°C	P _D	1.56 0.012	W W/°C
Operating and Storage Junction Temperature Range	T _J , T _{stg}	-65 to +150	°C
ESD – Human Body Model	HBM	3B	V
ESD – Machine Model	MM	С	V

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	8.3	°C/W
Thermal Resistance, Junction-to-Ambient*	R_{\thetaJA}	80	°C/W
Lead Temperature for Soldering Purposes	ΤL	260	°C

*These ratings are applicable when surface mounted on the minimum pad sizes recommended.

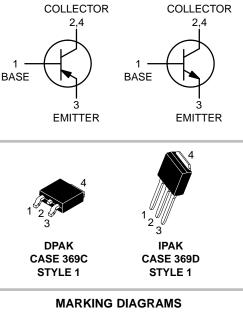


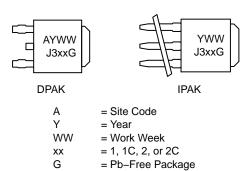
ON Semiconductor®

www.onsemi.com

SILICON POWER TRANSISTORS 3 AMPERES 40 AND 100 VOLTS 15 WATTS

COMPLEMENTARY





ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 8 of this data sheet.

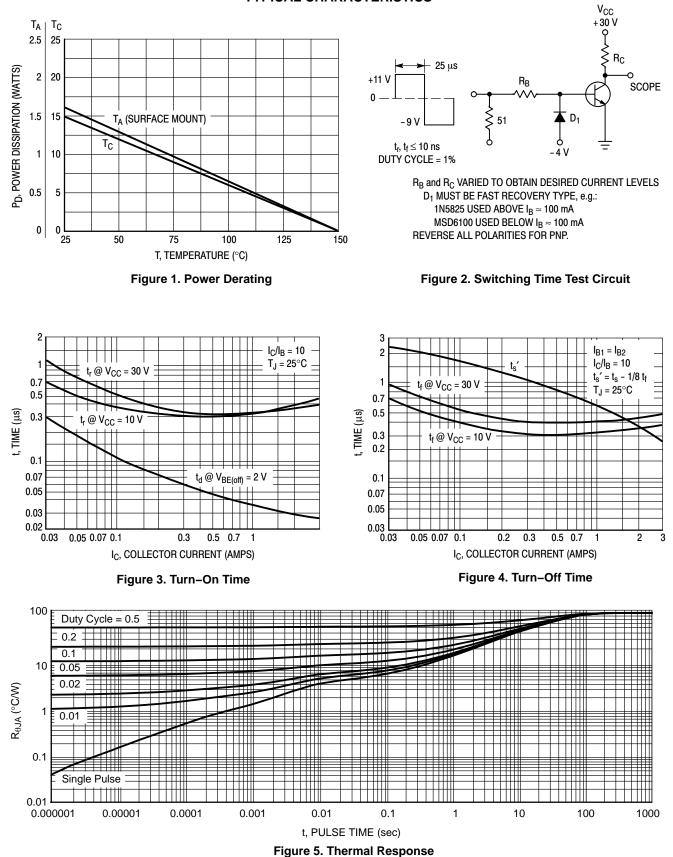
ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
DFF CHARACTERISTICS			-	
Collector–Emitter Sustaining Voltage (Note 1) (I _C = 30 mAdc, I _B = 0) MJD31, MJD32 MJD31C, MJD32C	V _{CEO(sus)}	40 100		Vdc
Collector Cutoff Current $(V_{CE} = 40 \text{ Vdc}, I_B = 0)$ MJD31, MJD32 $(V_{CE} = 60 \text{ Vdc}, I_B = 0)$ MJD31C, MJD32C	I _{CEO}	_	50 50	μAdc
Collector Cutoff Current (V_{CE} = Rated V_{CEO} , V_{EB} = 0)	ICES	-	20	μAdc
Emitter Cutoff Current ($V_{BE} = 5 \text{ Vdc}, I_C = 0$)	I _{EBO}	_	1	mAdc
DN CHARACTERISTICS (Note 1)	•			
DC Current Gain ($I_C = 1 \text{ Adc}, V_{CE} = 4 \text{ Vdc}$) ($I_C = 3 \text{ Adc}, V_{CE} = 4 \text{ Vdc}$)	h _{FE}	25 10	_ 50	
Collector–Emitter Saturation Voltage $(I_C = 3 \text{ Adc}, I_B = 375 \text{ mAdc})$	V _{CE(sat)}	_	1.2	Vdc
Base–Emitter On Voltage (I _C = 3 Adc, V _{CE} = 4 Vdc)	V _{BE(on)}	_	1.8	Vdc

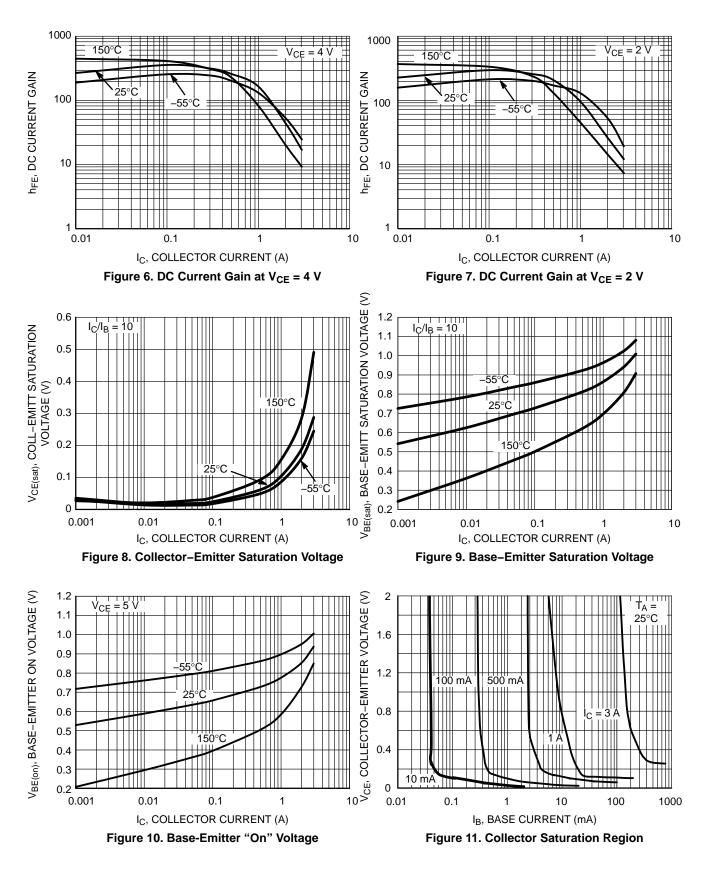
Current Gain – Bandwidth Product (Note 2) (I _C = 500 mAdc, V _{CE} = 10 Vdc, f _{test} = 1 MHz)	f _T	3	-	MHz
Small–Signal Current Gain (I _C = 0.5 Adc, V _{CE} = 10 Vdc, f = 1 kHz)	h _{fe}	20	_	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions. 1. Pulse Test: Pulse Width \leq 300 µs, Duty Cycle \leq 2%. 2. $f_T = |h_{fe}| \cdot f_{test}$.

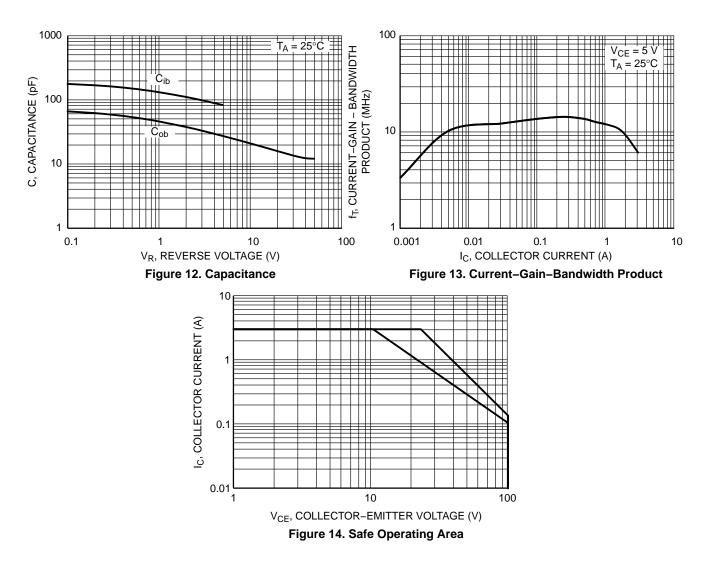
TYPICAL CHARACTERISTICS



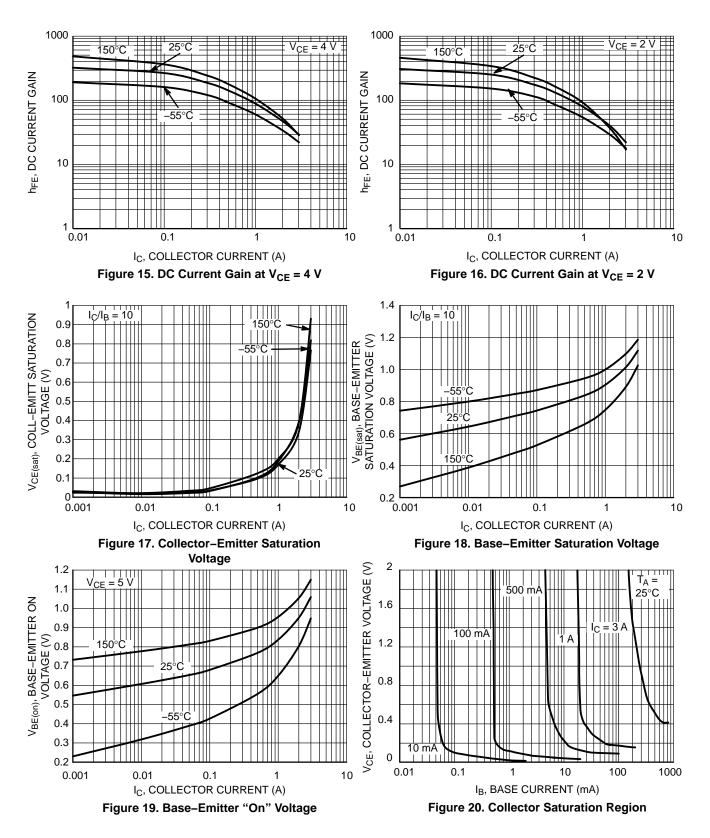
TYPICAL CHARACTERISTICS – MJD31, MJD31C (NPN)



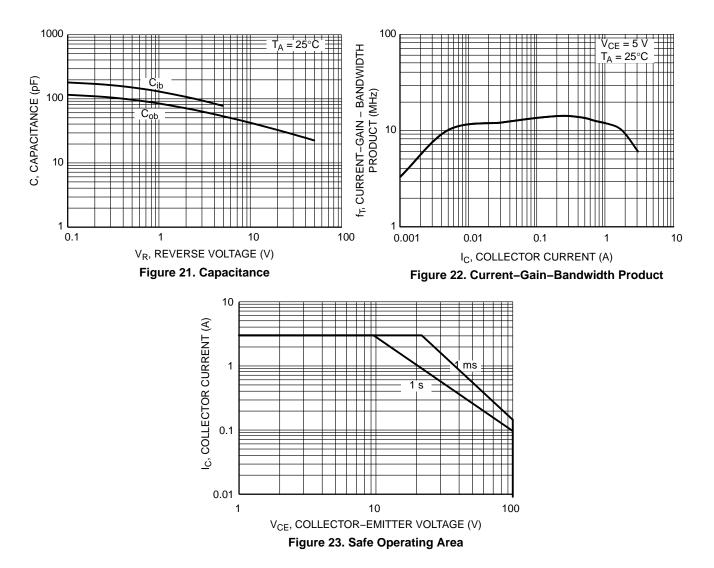
TYPICAL CHARACTERISTICS - MJD31, MJD31C (NPN)



TYPICAL CHARACTERISTICS – MJD32, MJD32C (PNP)



TYPICAL CHARACTERISTICS



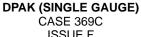
ORDERING INFORMATION

Device	Package Type	Package	Shipping [†]
MJD31CG	DPAK (Pb-Free)	369C	75 Units / Rail
NJVMJD31CG*	DPAK (Pb–Free)	369C	75 Units / Rail
MJD31C1G	IPAK (Pb–Free)	369D	75 Units / Rail
MJD31CRLG	DPAK (Pb–Free)	369C	1,800 / Tape & Reel
NJVMJD31CRLG*	DPAK (Pb–Free)	369C	1,800 / Tape & Reel
MJD31CT4G	DPAK (Pb–Free)	369C	2,500 / Tape & Reel
NJVMJD31CT4G*	DPAK (Pb–Free)	369C	2,500 / Tape & Reel
MJD31T4G	DPAK (Pb–Free)	369C	2,500 / Tape & Reel
NJVMJD31T4G*	DPAK (Pb–Free)	369C	2,500 / Tape & Reel
MJD32CG	DPAK (Pb–Free)	369C	75 Units / Rail
NJVMJD32CG*	DPAK (Pb–Free)	369C	75 Units / Rail
MJD32CRLG	DPAK (Pb-Free)	369C	1,800 / Tape & Reel
MJD32CT4G	DPAK (Pb–Free)	369C	2,500 / Tape & Reel
NJVMJD32CT4G*	DPAK (Pb-Free)	369C	2,500 / Tape & Reel
MJD32RLG	DPAK (Pb-Free)	369C	1,800 / Tape & Reel
MJD32T4G	DPAK (Pb-Free)	369C	2,500 / Tape & Reel
NJVMJD32T4G*	DPAK (Pb–Free)	369C	2,500 / Tape & Reel

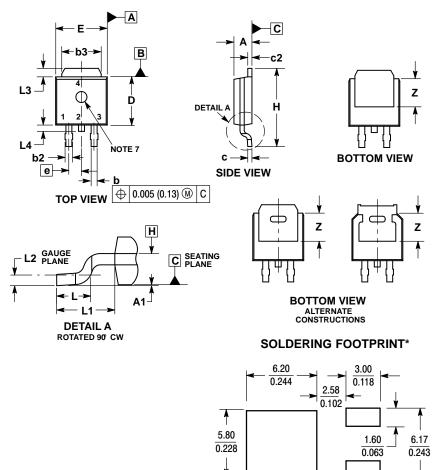
+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.
 *NJV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC–Q101 Qualified and PPAP

Capable.

PACKAGE DIMENSIONS







NOTES:

- I. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: INCHES.
 3. THERMAL PAD CONTOUR OPTIONAL WITHIN DI-MENSIONS b3, L3 and Z.
 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.006 INCHES PER SIDE.
 5. DIMENSIONS ON DE FARE NOTE AT THE
- DIMENSIONS D AND E ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
 DATUMS A AND B ARE DETERMINED AT DATUM

PLANE H. 7. OPTIONAL MOLD FEATURE

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
Α	0.086	0.094	2.18	2.38
A1	0.000	0.005	0.00	0.13
b	0.025	0.035	0.63	0.89
b2	0.028	0.045	0.72	1.14
b3	0.180	0.215	4.57	5.46
С	0.018	0.024	0.46	0.61
c2	0.018	0.024	0.46	0.61
D	0.235	0.245	5.97	6.22
Е	0.250	0.265	6.35	6.73
е	0.090 BSC		2.29 BSC	
н	0.370	0.410	9.40	10.41
L	0.055	0.070	1.40	1.78
L1	0.114 REF		2.90 REF	
L2	0.020	BSC	0.51 BSC	
L3	0.035	0.050	0.89	1.27
L4		0.040		1.01
Ζ	0.155		3.93	

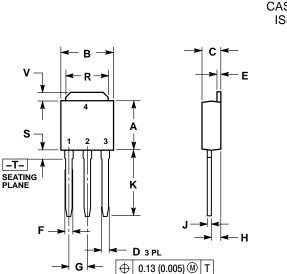
STYLE 1:

SCALE 3:1

PIN 1. BASE 2. COLLECTOR 3. EMITTER 4. COLLECTOR

 $[\]left(\frac{mm}{inches}\right)$ *For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS



IPAK CASE 369D ISSUE C

NOTES:

Ζ

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

CONTROLLING DIMENSION: INCH

	INCHES		MILLIMETE	
DIM	MIN	MAX	MIN	MAX
Α	0.235	0.245	5.97	6.35
В	0.250	0.265	6.35	6.73
С	0.086	0.094	2.19	2.38
D	0.027	0.035	0.69	0.88
Е	0.018	0.023	0.46	0.58
F	0.037	0.045	0.94	1.14
G	0.090 BSC		2.29 BSC	
н	0.034	0.040	0.87	1.01
J	0.018	0.023	0.46	0.58
к	0.350	0.380	8.89	9.65
R	0.180	0.215	4.45	5.45
S	0.025	0.040	0.63	1.01
٧	0.035	0.050	0.89	1.27
Ζ	0.155		3.93	

STYLE 1: PIN 1. BASE

2. COLLECTOR

3. EMITTER 4. COLLECTOR

ON Semiconductor and are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns me rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at www.onsemi.com/site/pdl/Patent_Marking.pdf. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor dates sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights or the rights of others. ON Semiconductor and its officers, employees, subsidiaries, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized application. Buyer shall indemnify and hold ON Semiconductor and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable at

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT

Literature Distribution Center for ON Semiconductor 19521 E. 32nd Pkwy, Aurora, Colorado 80011 USA Phone: 303–675–2175 or 800–344–3860 Toll Free USA/Canada Fax: 303–675–2176 or 800–344–3867 Toll Free USA/Canada Email: orderlit@onsemi.com N. American Technical Support: 800–282–9855 Toll Free USA/Canada Europe, Middle East and Africa Technical Support: Descent 201 02 700 0010

Phone: 421 33 790 2910 Japan Customer Focus Center Phone: 81–3–5817–1050 ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

ON Semiconductor:

MJD31C1G MJD31CG MJD31CRLG MJD31CT4G MJD31T4G MJD32CG MJD32CRLG MJD32CT4G MJD32RLG MJD32T4G NJVMJD32CT4G NJVMJD32CG